Data sheet acquired from Harris Semiconductor
SCHS020C – Revised October 2003

CD4009UB, CD4010B Types

CMOS Hex Buffers/Converters

High-Voltage Types (20-Volt Rating)

Inverting Type: CD4009UB
Non-Inverting Type: CD4010B

■ CD4009UB and CD4010B Hex Buffer/Converters may be used as CMOS to TTL or DTL logic-level converters or CMOS high-sink-current drivers.

The CD4049UB and CD4050B are preferred hex buffer replacements for the CD4009UB and CD4010B, respectively, in all applications except multiplexers. For applications not requiring high sink current or voltage conversion, the CD4069UB Hex Inverter is recommended.

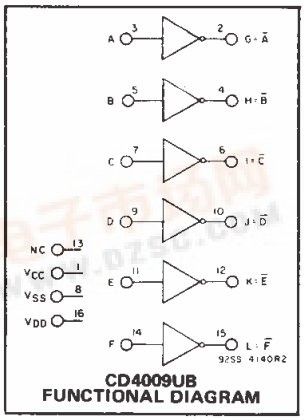
The CD4009UB and CD4010B types are supplied in 16-lead hermetic dual-in-line ceramic packages (F3A suffix), 16-lead dual-in-line plastic packages (E suffix), 16-lead small-outline packages (M, M96, MT, and NSR suffixes), and 16-lead thin shink small-outline packages (PW and PWR suffixes).

Features:

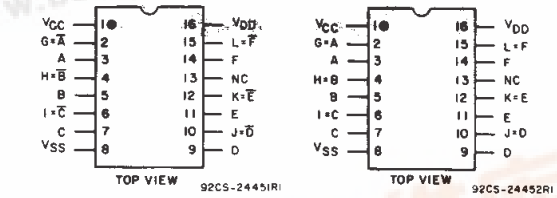
- 100% tested for quiescent current at 20 V
- Maximum input current of 1 μA at 18 V over full package-temperature range; 100 nA at 18 V and 25°C
- 5-V, 10-V, and 15-V parametric ratings

Applications:

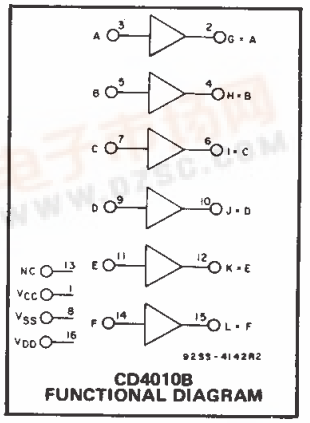
- CMOS to DTL/TTL hex converter
- CMOS current "sink" or "source" driver
- CMOS high-to-low logic-level converter
- Multiplexer — 1 to 6 or 6 to 1



CD4009UB
FUNCTIONAL DIAGRAM



TERMINAL ASSIGNMENTS



CD4010B
FUNCTIONAL DIAGRAM

MAXIMUM RATINGS, *Absolute-Maximum Values:*

DC SUPPLY-VOLTAGE RANGE, (V_{DD})
Voltages referenced to V_{SS} Terminal) ..... -0.5V to +20V
INPUT VOLTAGE RANGE, ALL INPUTS ..... -0.5V to V_{DD} +0.5V
DC INPUT CURRENT, ANY ONE INPUT ..... ±10mA
POWER DISSIPATION PER PACKAGE (P_D):
For T_A = -55°C to +100°C 500mW
For T_A = +100°C to +125°C ..... Derate Linearity at 12mW/°C to 200mW
DEVICE DISSIPATION PER OUTPUT TRANSISTOR
FOR T_A = FULL PACKAGE-TEMPERATURE RANGE (All Package Types) 100mW
OPERATING-TEMPERATURE RANGE (T_A) ..... -55°C to +125°C
STORAGE TEMPERATURE RANGE (T_{stg}) ..... -65°C to +150°C
LEAD TEMPERATURE (DURING SOLDERING):
At distance 1/16 ± 1/32 inch (1.59 ± 0.79mm) from case for 10s max ..... +265°C

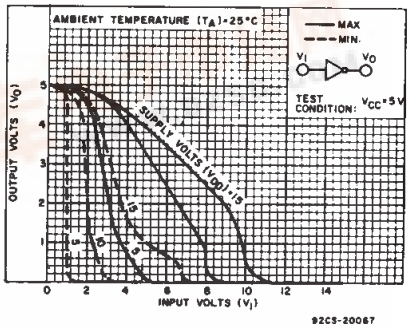


Fig. 3 — Minimum and maximum voltage transfer characteristics—CD4009UB.

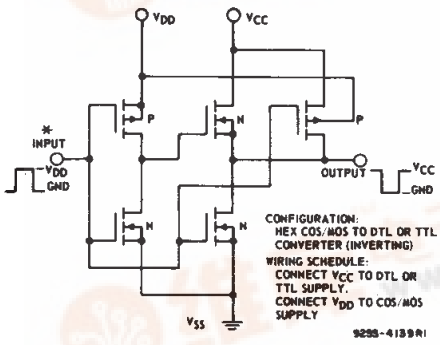


Fig. 1 — Schematic diagram of CD4009UB— 1 of 6 identical stages.

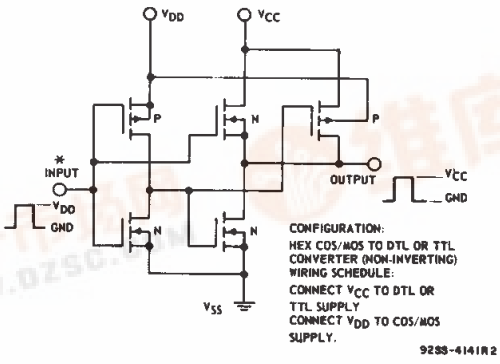
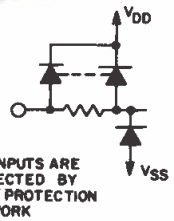


Fig. 2 — Schematic diagram of CD4010B— 1 of 6 identical stages.



RECOMMENDED OPERATING CONDITIONS

For maximum reliability, nominal operating conditions should be selected so that operation is always within the following ranges:

CHARACTERISTIC	LIMITS		UNITS
	MIN.	MAX.	
Supply-Voltage Range (For T_A = Full Package Temperature Range), V_{DD}	3	18	V
V_{CC}*	3	V_{DD}	
Input Voltage Range (V_I)	V_{CC}*	V_{DD}	V

*The CD4009UB and CD4010B have high-to-low level voltage conversion capability but not low-to-high level, therefore it is recommended that $V_{DD} \geq V_I \geq V_{CC}$.

STATIC ELECTRICAL CHARACTERISTICS

CHARACTERISTIC	CONDITIONS			LIMITS AT INDICATED TEMPERATURES (°C)							UNITS
	V_O (V)	V_{IN} (V)	V_{DD} (V)	−55	−40	+85	+125	+25 Min.	+25 Typ.	+25 Max.	
Quiescent Device Current, I_{DD} Max.	–	0,5	5	1	1	30	30	–	0.02	1	μA
	–	0,10	10	2	2	60	60	–	0.02	2	
	–	0,15	15	4	4	120	120	–	0.02	4	
	–	0,20	20	20	20	600	600	–	0.04	20	
Output Low (Sink) Current I_{OL} Min.	0.4	0,5	4.5	3.2	3.1	2.1	1.8	2.6	3.4	–	mA
	0.4	0,5	5	3.75	3.6	2.4	2.1	3	4	–	
	0.5	0,10	10	10	9.6	6.4	5.6	8	10	–	
	1.5	0,15	15	30	40	19	16	24	36	–	
Output High (Source) Current I_{OH} Min.	4.6	0,5	5	−0.25	−0.23	−0.18	−0.15	−0.2	−0.4	–	
	2.5	0,5	5	−1	−0.9	−0.65	−0.58	−0.8	−1.6	–	
	9.5	0,10	10	−0.55	−0.5	−0.38	−0.33	−0.45	−0.9	–	
	13.5	0,15	15	−1.65	−1.6	−1.25	−1.1	−1.5	−3	–	
Output Voltage: Low-Level, V_{OL} Max.	–	0,5	5	0.05				–	0	0.05	V
	–	0,10	10	0.05					0	0.05	
	–	0,15	15	0.05				–	0	0.05	
Output Voltage: High-Level, V_{OH} Min.	–	0,5	5	4.95				4.95	5	–	
	–	0,10	10	9.95				9.95	10	–	
	–	0,15	15	14.95				14.95	15	–	
Input Low Voltage: V_{IL} Max. CD4009UB	4.5	–	5	1				–	–	1	V
	9	–	10	2				–	–	2	
	13.5	–	15	2.5				–	–	2.5	
Input Low Voltage: V_{IL} Max. CD4010B	0.5	–	5	1.5				–	–	1.5	
	1	–	10	3				–	–	3	
	1.5	–	15	4				–	–	4	
Input High Voltage: V_{IH} Min. CD4009UB	0.5	–	5	4				4	–	–	
	1	–	10	8				8	–	–	
	1.5	–	15	12.5				12.5	–	–	
Input High Voltage: V_{IH} Min. CD4010B	4.5	–	5	3.5				3.5	–	–	
	9	–	10	7				7	–	–	
	13.5	–	15	11				11	–	–	
Input Current, I_{IN} Max.	–	0,18	18	±0.1	±0.1	±1	±1	–	$\pm 10^{-5}$	±0.1	μA

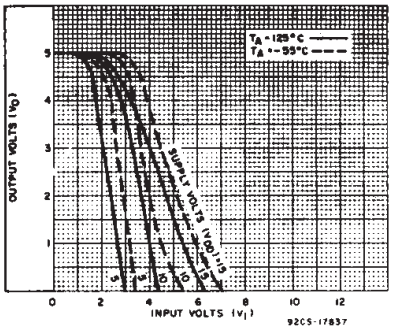


Fig. 4 – Typical voltage transfer characteristics as function of temp.–CD4009UB.

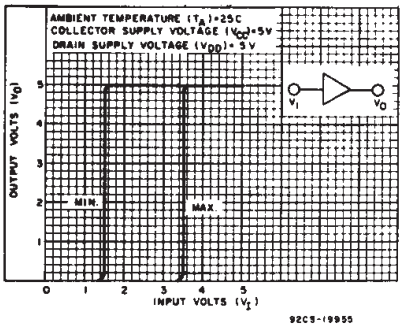


Fig. 5 – Minimum and maximum voltage transfer characteristics (V_{DD}=5)–CD4010B.

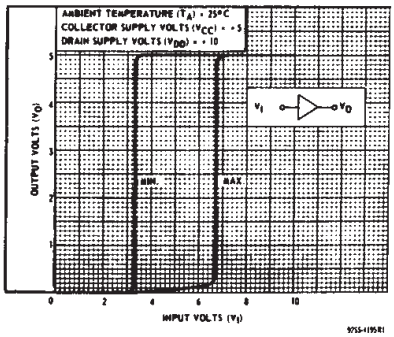


Fig. 6 – Minimum and maximum voltage transfer characteristics (V_{DD}=10)–CD4010B.

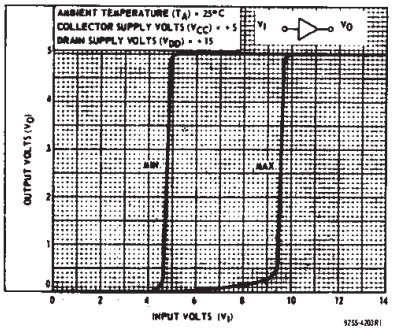


Fig. 7 – Minimum and maximum voltage transfer characteristics (V_{DD}=15)–CD4010B.

DYNAMIC ELECTRICAL CHARACTERISTICS *at T_A=25°C; Input t_r, t_f=20 ns, C_L=50 pF, R_L=200 KΩ*

CHARACTERISTIC	CONDITIONS V_{DD} (V)	V_I (V)	V_{CC} (V)	LIMITS ALL PKGS TYP.	MAX.	UNIT
Propagation Delay Time: Low-to-High, t_{PLH}	5	5	5	70	140	ns
	10	10	10	40	80	
CD4009UB	10	10	5	35	70	
	15	15	15	30	60	
	15	15	5	30	60	
	5	5	5	100	200	ns
	10	10	10	50	100	
CD4010B	10	10	5	50	100	
	15	15	15	35	70	
	15	15	5	35	70	
High-to-Low, t_{PHL}	5	5	5	30	60	ns
	10	10	10	20	40	
CD4009UB	10	10	5	15	30	
	15	15	15	15	30	
	15	15	5	10	20	
	5	5	5	65	130	ns
	10	10	10	35	70	
CD4010B	10	10	5	30	70	
	15	15	15	25	50	
	15	15	5	20	40	
Transition Time: Low-to-High, t_{TLH}	5	5	5	150	350	ns
	10	10	10	75	150	
	15	15	15	55	110	
High-to-Low, t_{THL}	5	5	5	35	70	ns
	10	10	10	20	40	
	15	15	15	15	30	
Input Capacitance, C_{IN} CD4009UB	–	–	–	15	22.5	pF
CD4010B	–	–	–	5	7.5	

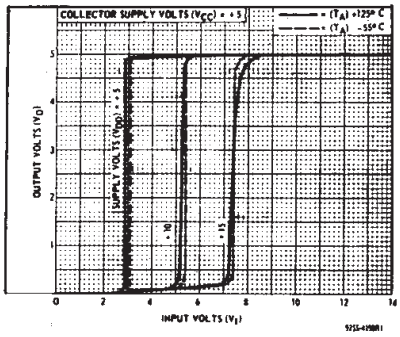


Fig. 8 – Typical voltage transfer characteristics as a function of temperature—CD4010B.

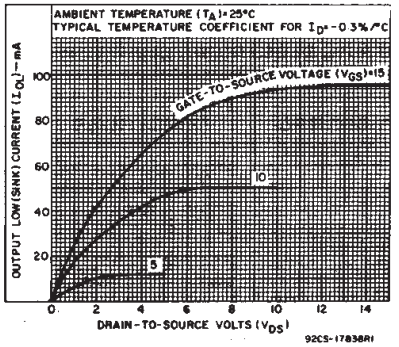


Fig. 9 – Typical output low (sink) current characteristics.

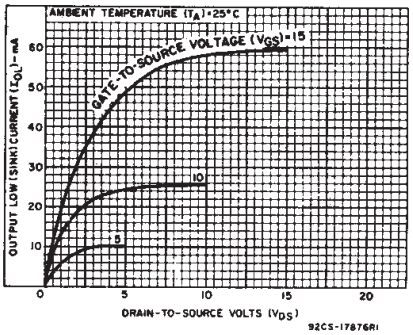


Fig. 10 – Minimum output low (sink) current characteristics.

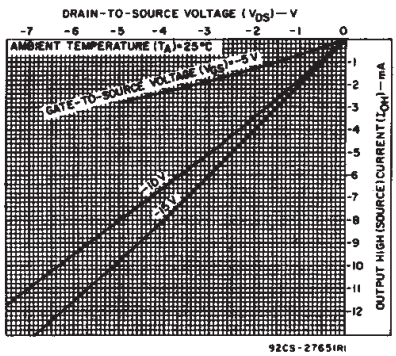


Fig. 11 – Typical output high (source) current characteristics.

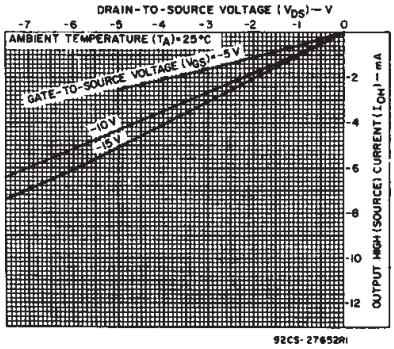


Fig. 12 – Minimum output high (source) current characteristics.

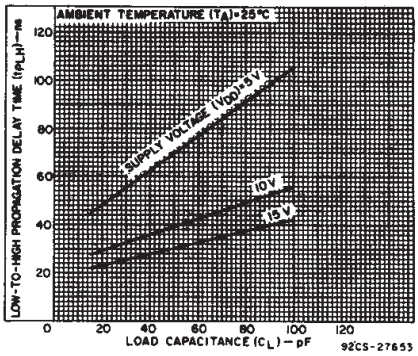


Fig. 13 – Typical low-to-high propagation delay time vs. load capacitance (CD4009UB).

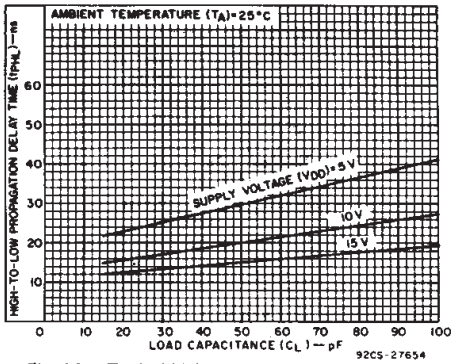


Fig. 14 — Typical high-to-low propagation delay time vs. load capacitance (CD4009UB).

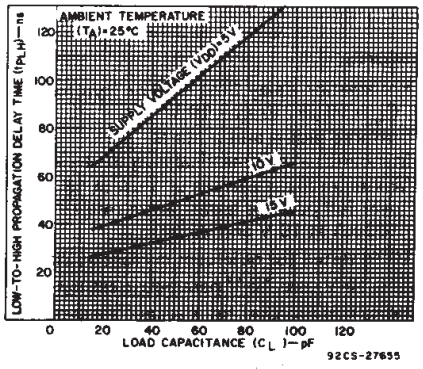


Fig. 15 — Typical low-to-high propagation delay time vs. load capacitance (CD4010B).

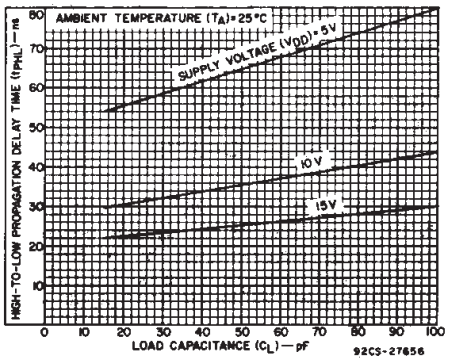


Fig. 16 — Typical high-to-low propagation delay time vs. load capacitance (CD4010B).

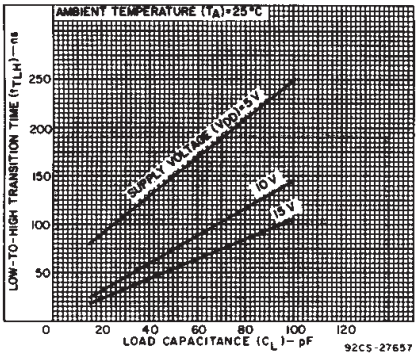


Fig. 17 — Typical low-to-high transition time vs. load capacitance.

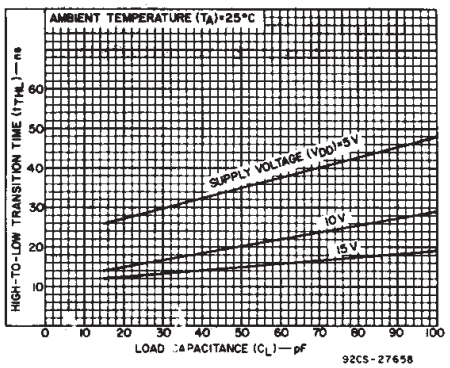


Fig. 18 — Typical high-to-low transition time vs. load capacitance.

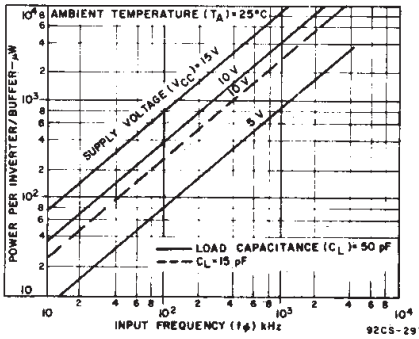


Fig. 19 — Typical dissipation characteristics.

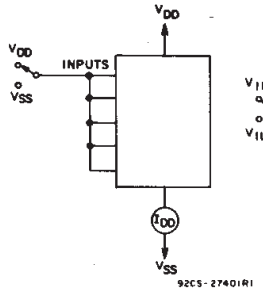


Fig. 20 — Quiescent device current test circuit.

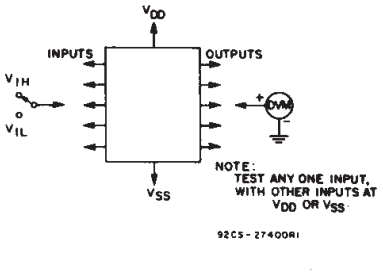


Fig. 21 — Noise immunity test circuit.

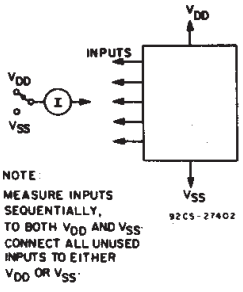
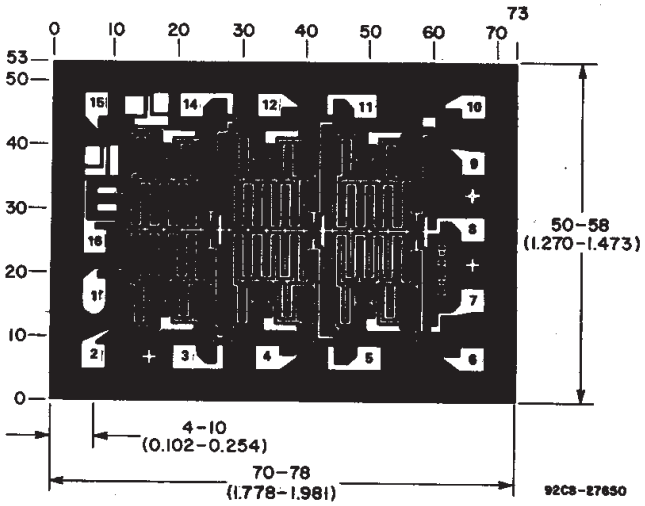


Fig. 22 — Input current test circuit.



Dimensions in parentheses are in millimeters and are derived from the basic inch dimensions as indicated. Grid Graduations Are In Mils (10^{-3} Inch)

Photograph of chip for CD4009UB. Dimensions and pad layout for CD4010B are identical.

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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/ Ball Finish	MSL Pea
89264UKB3T	OBSOLETE	CFP	WR	16		TBD	Call TI	Call TI
CD4009UBE	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg
CD4009UBEE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg
CD4009UBF	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg
CD4009UBF3A	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg
CD4009UBM	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260
CD4009UBME4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260
CD4009UBMG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260
CD4009UBMT	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260
CD4009UBMTE4	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260
CD4009UBMTG4	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260
CD4009UBPWR	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260
CD4009UBPWRE4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260
CD4009UBPWRG4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260
CD4010BE	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg
CD4010BEE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg
CD4010BF	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg
CD4010BF3A	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg
CD4010BM	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260

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Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/ Ball Finish	MSL Pea
CD4010BM96	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260
CD4010BM96E4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260
CD4010BM96G4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260
CD4010BME4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260
CD4010BMG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260
CD4010BMT	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260
CD4010BMTE4	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260
CD4010BMTG4	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260
CD4010BNSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260
CD4010BNSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260
CD4010BNSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260
CD4010BPW	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260
CD4010BPWE4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260
CD4010BPWG4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260
CD4010BPWR	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260
CD4010BPWRE4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260
CD4010BPWRG4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.
information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all
lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable fo
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package,
the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retard
in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical an
TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for releas

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Cu

OTHER QUALIFIED VERSIONS OF CD4009UB, CD4009UB-MIL, CD4010B, CD4010B-MIL :

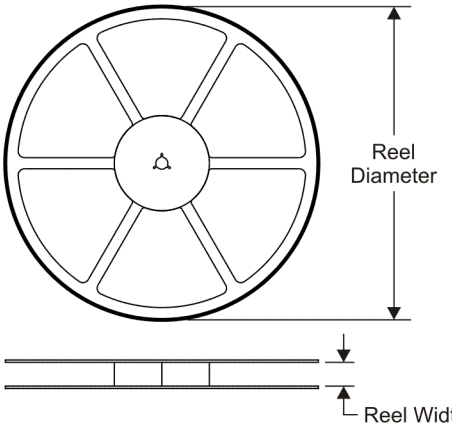
- Catalog: CD4009UB, CD4010B
- Automotive: CD4010B-Q1, CD4010B-Q1
- Military: CD4009UB-MIL, CD4010B-MIL

NOTE: Qualified Version Definitions:

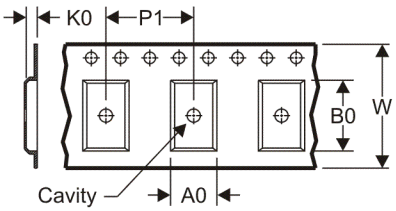
- Catalog - TI's standard catalog product
- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects
- Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION

REEL DIMENSIONS

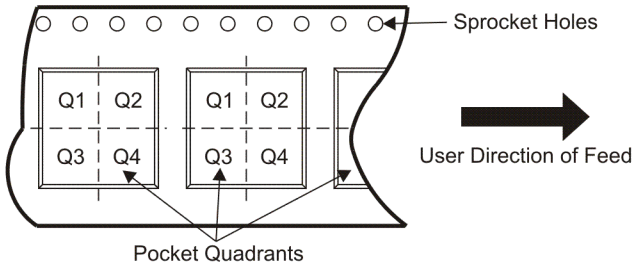


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

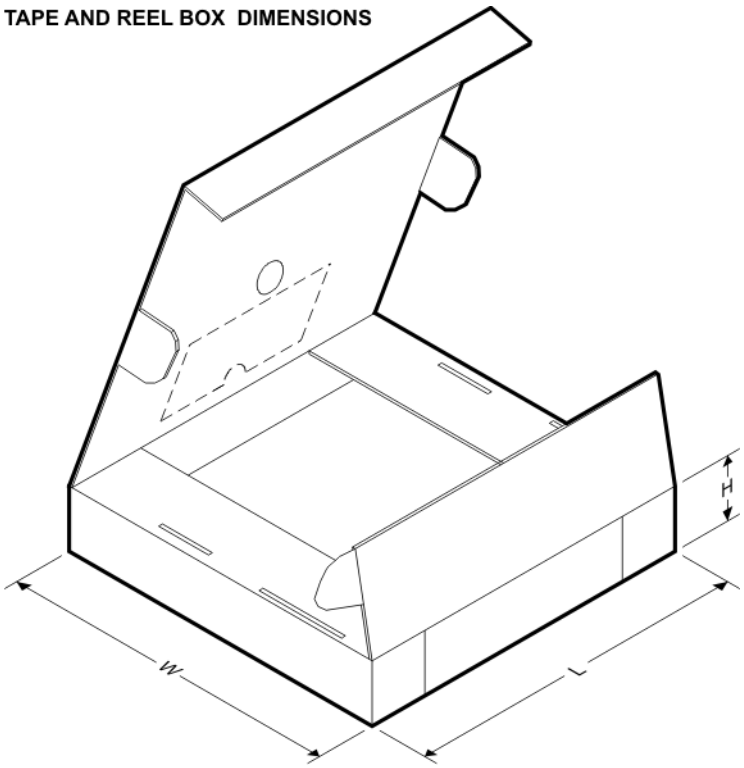
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD4009UBPWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
CD4010BM96	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
CD4010BNSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
CD4010BPWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS

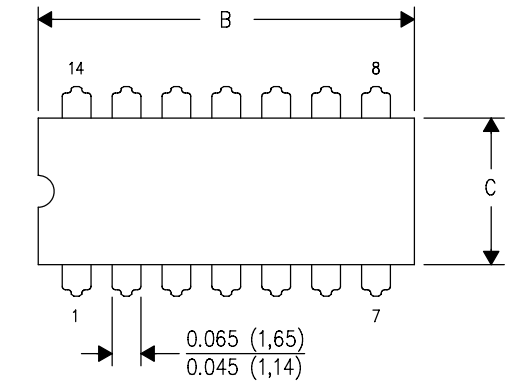


*All dimensions are nominal

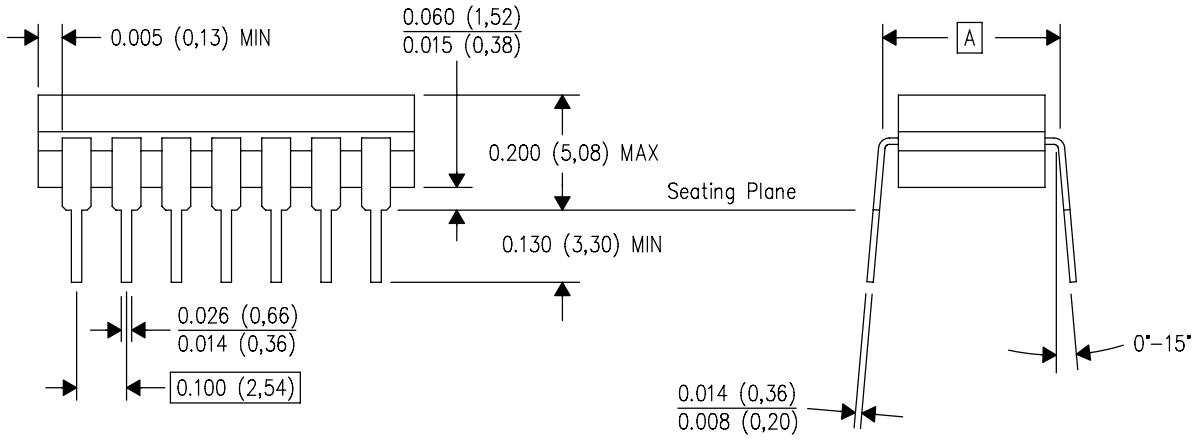
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CD4009UBPWR	TSSOP	PW	16	2000	346.0	346.0	29.0
CD4010BM96	SOIC	D	16	2500	333.2	345.9	28.6
CD4010BNSR	SO	NS	16	2000	346.0	346.0	33.0
CD4010BPWR	TSSOP	PW	16	2000	346.0	346.0	29.0

J (R–GDIP–T**) CERAMIC DUAL IN–LINE PACKAGE

14 LEADS SHOWN



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)

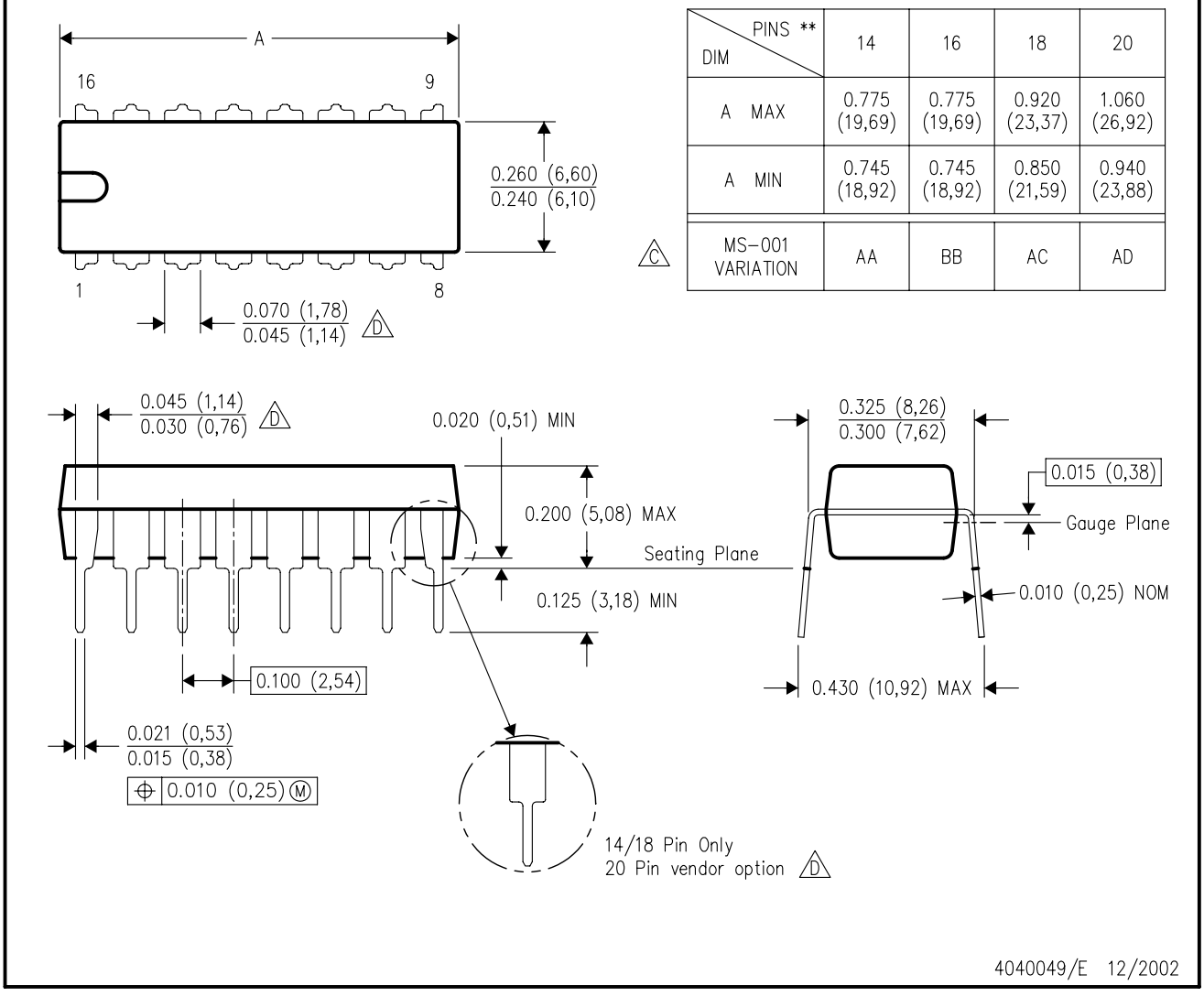


4040083/F 03/03

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package is hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
E. Falls within MIL STD 1835 GDIP1–T14, GDIP1–T16, GDIP1–T18 and GDIP1–T20.

N (R–PDIP–T**) PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN

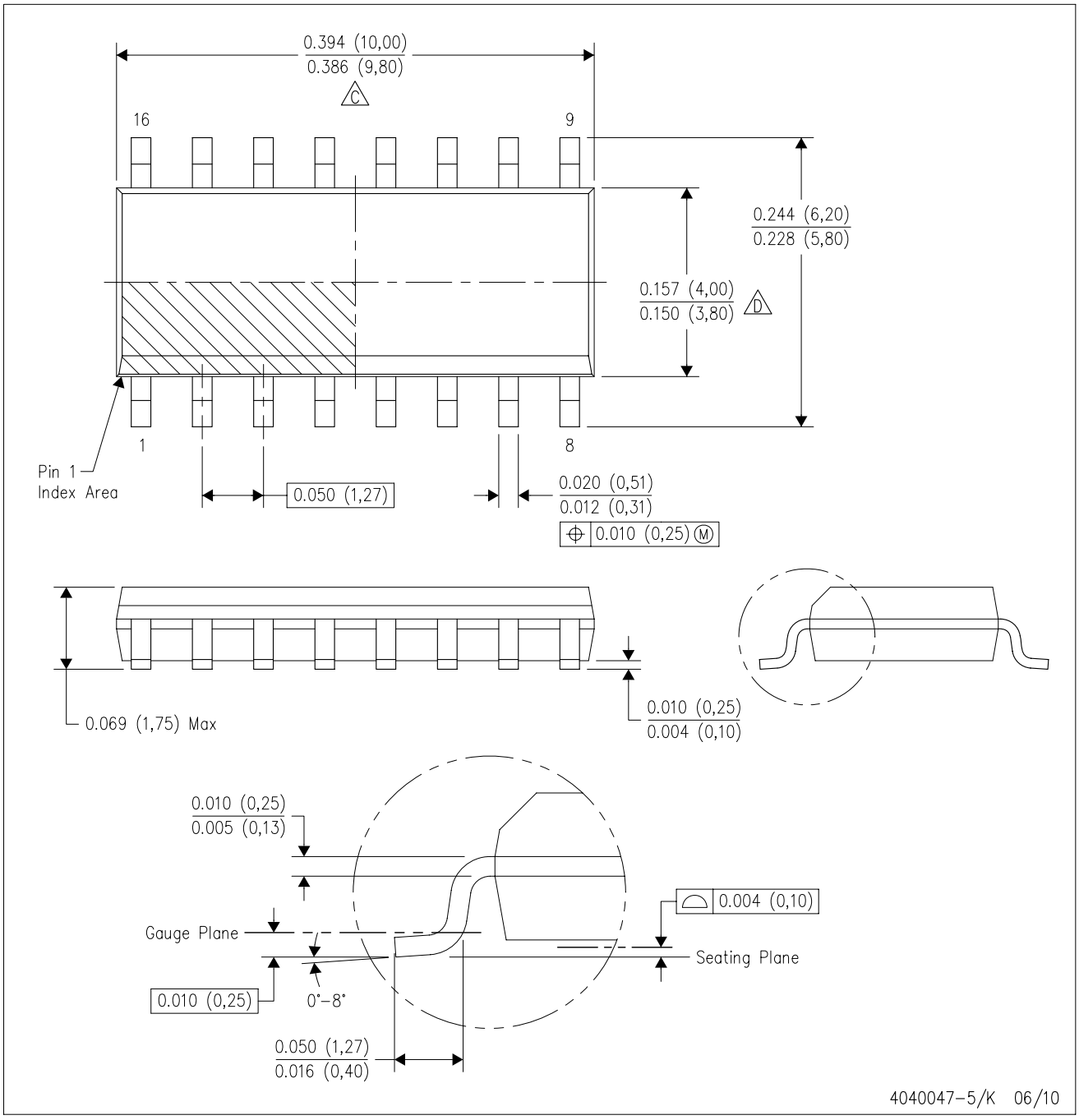


DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS–001 VARIATION	AA	BB	AC	AD

4040049/E 12/2002

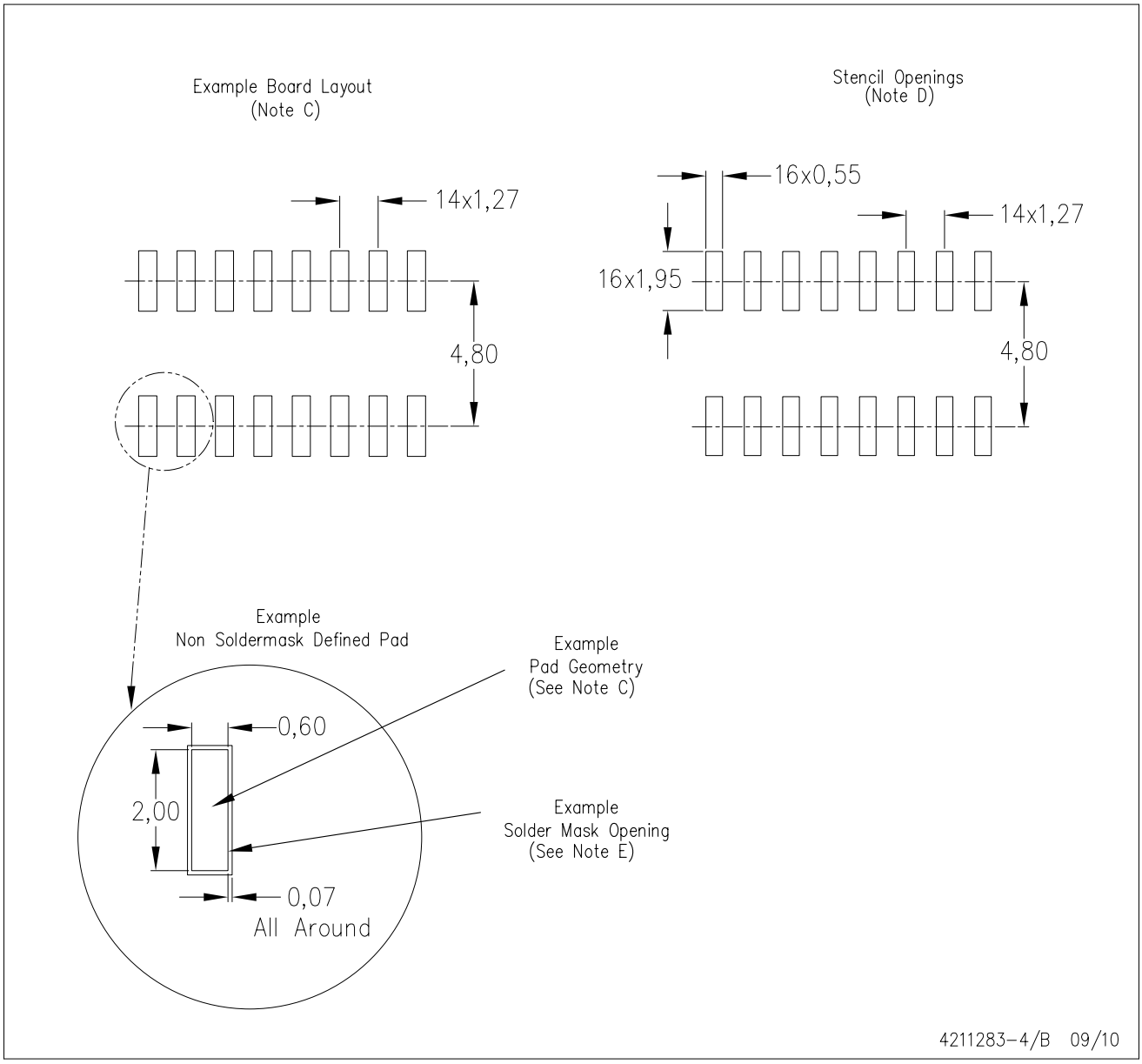
NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001, except 18 and 20 pin minimum body length (Dim A).
D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R-PDSO-G16) PLASTIC SMALL-OUTLINE PACKAGE



NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
D. Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
E. Reference JEDEC MS-012 variation AC.

D (R–PDSO–G16) PLASTIC SMALL OUTLINE

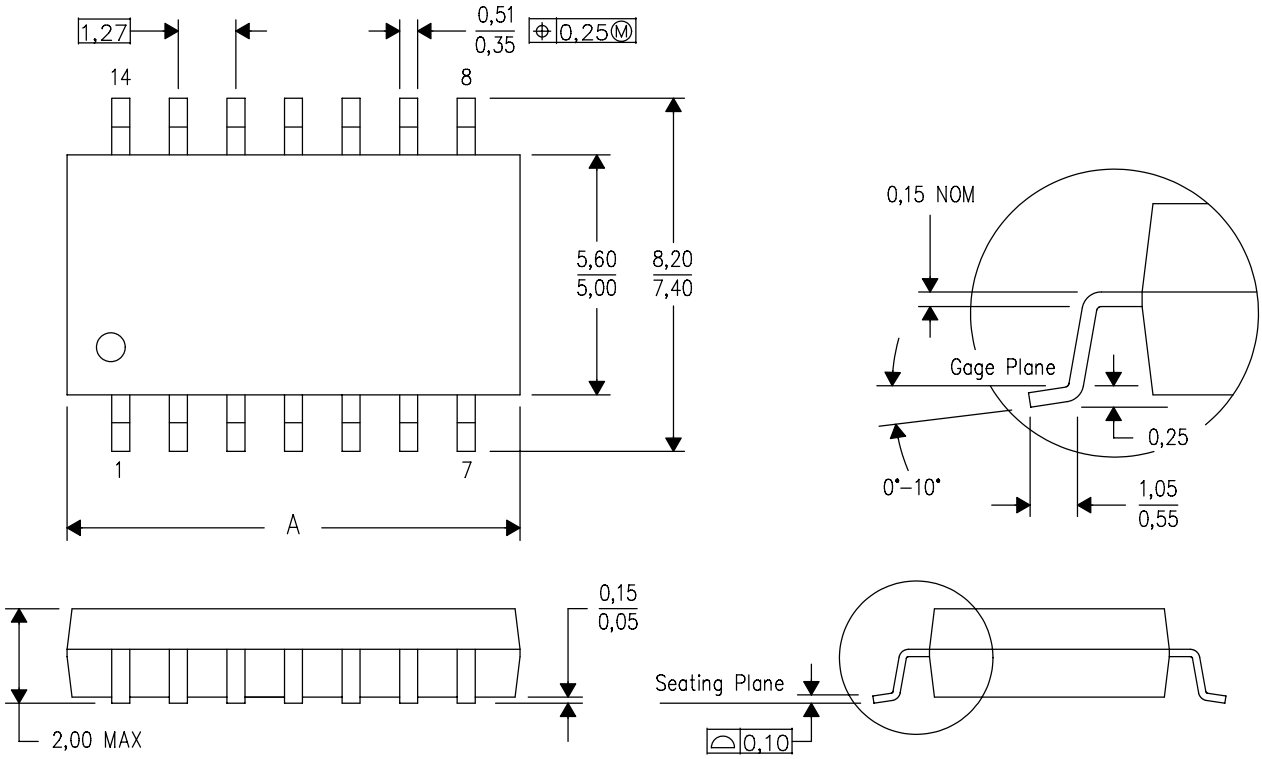


NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Publication IPC–7351 is recommended for alternate designs.
D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC–7525 for other stencil recommendations.
E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

MECHANICAL DATA

NS (R-PDSO-G)** **PLASTIC SMALL-OUTLINE PACKAGE**

14-PINS SHOWN



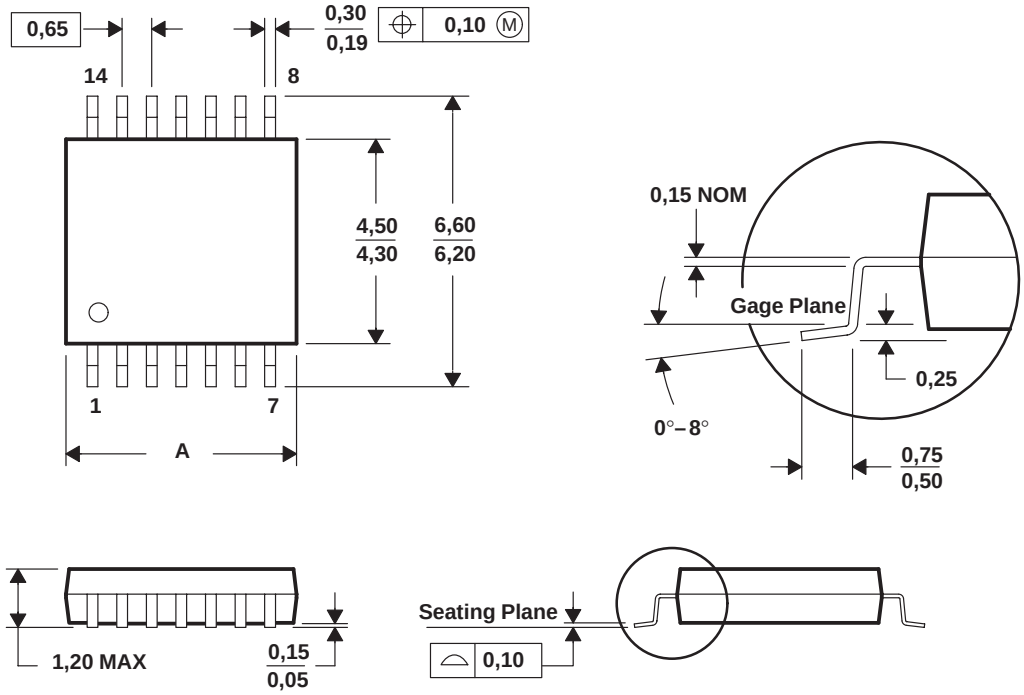
DIM \ PINS **	14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70

4040062/C 03/03

NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

PW (R-PDSO-G)** **PLASTIC SMALL-OUTLINE PACKAGE**

14 PINS SHOWN

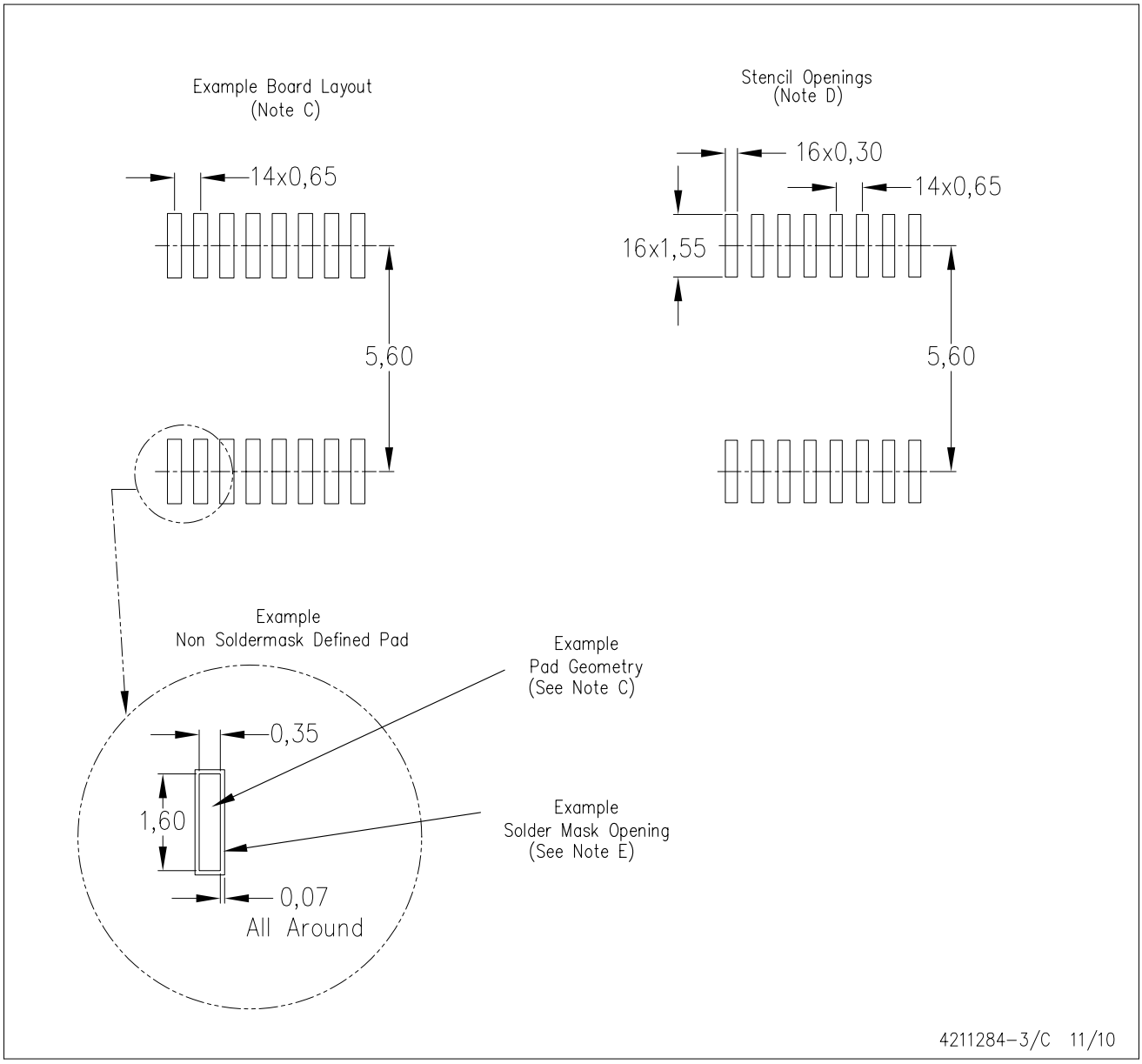


DIM \ PINS **	8	14	16	20	24	28
A MAX	3,10	5,10	5,10	6,60	7,90	9,80
A MIN	2,90	4,90	4,90	6,40	7,70	9,60

4040064/F 01/97

NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
D. Falls within JEDEC MO-153

PW (R-PDSO-G16) PLASTIC SMALL OUTLINE



NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Publication IPC-7351 is recommended for alternate designs.
D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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